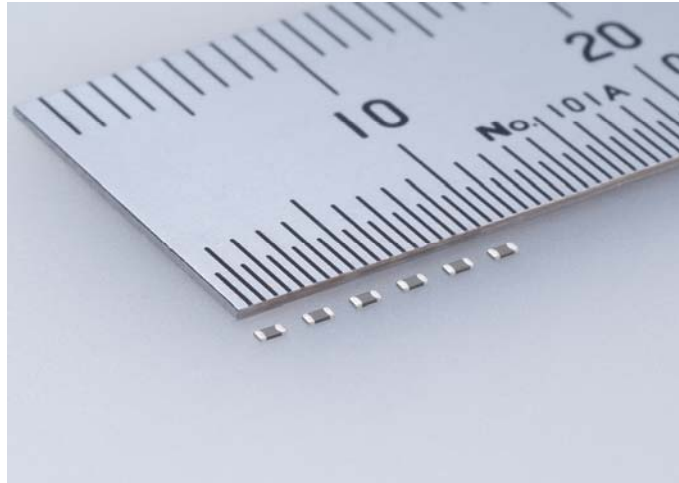


For immediate release

Taiyo Yuden's 0.22mm-Thin Multilayer Ceramic Capacitor Achieves Industry-Leading Capacitance Value of 1 μ F

*0.47 μ F Capacitance even in a 0.15mm Profile
Enables Mounting for Component-Embedded Substrates*



TOKYO, April 26, 2010 — Taiyo Yuden Co., Ltd. today announced details of the commercial release of the “AMK105BJ105MC” (1.0 x 0.5 x 0.22mm), achieving a capacitance value of 1 μ F at a thickness of 0.22mm and the “AMC105BJ474MH” (1.0 x 0.5 x 0.15mm), achieving a capacitance value of 0.47 μ F at a thickness of 0.15mm (thicknesses are maximum values), both in an EIA 0402 size ultra low-profile multilayer ceramic capacitor contributing to higher density mounting for mobile devices which are becoming increasingly compact and thin. Each product more than doubles the capacitance value of the company's existing products, achieving industry-leading high capacitance at the same size and profile. The introduction of these products augments Taiyo Yuden's lineup of ultra low-profile high-value multilayer ceramic capacitors, responding to the high performance needs of more compact, thinner mobile devices.

Mass production of both products will begin from May 2010 at the company's Tamamura Plant in Gunma Prefecture, Japan at a combined output pace of 10 million units per month. The price for samples both products is 10 yen per unit.

Technology Background

Smaller, slimmer smartphones and high-end mobile phones with high-performance specs are becoming increasingly popular. The latest devices have larger LCD screens as well as more and better functions such as Internet connectivity, audio and visual entertainment, and high-quality photographic capabilities. As a result, low-profile surface-mount electronic component needs are growing. In this context, high-value multilayer ceramic capacitors for IC power lines are tending to be lower in height.

Furthermore, smaller devices and modules have given rise to high-density surface mount technologies including the component-embedded substrate technology used to make electronic

components for use inside printed circuit boards. For electronic components embedded in substrates, the need for lower profile products is greater than ever.

Since the release of its nickel-electrode high-value multilayer ceramic capacitor in 1984, Taiyo Yuden has worked to create ever more compact and higher value capacitors by developing material and thin layer technologies for multilayer ceramic capacitors. Those technologies were employed in the new low-profile multilayer ceramic capacitors, too, to achieve high capacitance values up to 1 μ F at a thickness of 0.22mm and up to 0.47 μ F at a thickness of 0.15mm both in an EIA 0402 size and more than double the capacitance value of the company’s existing products. External electrodes are applied with copper plating to achieve optimum mountability on component-embedded substrates for the “AMC105BJ474MH.”

Taiyo Yuden’s portfolio of low-profile multilayer ceramic capacitors is shown below:

Ordering code	Capacitance	Temperature Characteristic	Rated Voltage	Length [mm]	Width [mm]	Thickness [mm]	Remarks
AMK105BJ105MC	1 μ F	X5R	4V	1.0 \pm 0.05	0.5 \pm 0.05	0.20 \pm 0.02	
AMC105BJ474MH	0.47 μ F	X5R	4V	1.0 \pm 0.05	0.5 \pm 0.05	0.13 \pm 0.02	†

†: Copper plating type